

PacTechs announces new website launch

NAUEN, Germany: PacTech announces the launch of its newly revamped website. This newly redesigned website offers quick and easy access to essential information and features that offers a more comprehensive understanding of the innovative equipment portfolio and different wafer level packaging services. Now the website is connected to the new PacTech customer online center and also offers a chat function.

The website goes live today, April 8, 2022 and is located at the same address <http://www.pactech.com>

“We are excited about our new website launch with the higher usability and the solid information it provides for customer and partners to better understand PacTech’s technologies” said Thomas Oppert, Vice President Global Sales & Marketing of PacTech. “We believe that the new site will allow our visitor to have a very informative experience as we continue to grow and increase our market presence.”

About PacTech:

Advanced equipment manufacturer, wafer level packaging (WLP) subcontracting service provider and chemistry supplier specialized in electroless under bump metallization (UBM), solder balling and back-end services with more than 25 years of experience after spinning off from the Fraunhofer Institute for Reliability and Microintegration IZM in Berlin, Germany.

Mother company: Nagase & Co., Ltd. with headquarters in Tokyo, Japan

Facilities: Nauen, Germany (headquarters); Santa Clara, CA, USA & Penang, Malaysia

www.pactech.com